

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JEEHUN PARK	05/15/2019
HYUNSIK KIM	05/15/2019
JAEHYEON PARK	05/15/2019
SANGJIN LEE	05/15/2019
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Property Type	Number
Application Number:	16420130
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DATE SIGNED:	05/22/2019
Total Attachments: 2	
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ASSIGNMENT OF PATENT APPLICATION

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: APPARATUS FOR OPTIMIZING FLOW
ANALYSIS AND METHOD THEREFOR

Filing Date: May 22, 2019

Application No.: 16/420,130

WHEREAS, **DOOSAN HEAVY INDUSTRIES & CONSTRUCTION CO., LTD.**, located at 22, Doosanvolvo-ro, Seongsan-gu, Changwon-si, Gyeongsangnam-do, 51711 Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignees, and Assignees' successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignees as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns. Assignors hereby authorize and request INVENSTONE PATENT, LLC, 8408 Arlington BLVD Suite 203, FAIRFAX VA 22031 U.S.A., to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Legal Name of Inventor: PARK, Jeehun

Signature:  Date: May 15, 2019

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Legal Name of Inventor: KIM, Hyunsik

Signature: [Handwritten Signature] Date: May 15, 2019

Legal Name of Inventor: PARK, Jaehyeon

Signature: [Handwritten Signature] Date: May 15, 2019

Legal Name of Inventor: LEE, Sangjin

Signature: [Handwritten Signature] Date: May 15, 2019

